

ABSTRACT

PLASMA CHAMBER SYSTEM AND METHOD OF ASHING PHOTORESIST PATTERN FORMED ON SUBSTRATE HAVING LOW-K DIELECTRIC LAYER USING THE SAME

Disclosed is a plasma chamber system and method of ashing a photoresist pattern formed on a substrate having a low-K dielectric layer using the same. The plasma chamber system includes a process chamber, a wafer chuck arranged in the process chamber, a bottom radio-frequency power source electrically connected to the wafer chuck, a top electrode arranged on the wafer chuck, top Helmholtz coils arranged on the process chamber, and bottom Helmholtz coils arranged under the process chamber.

Fig. 2 is to be published